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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/722,394	11/28/2003	Hsin-Chang Wu	4425-336	7178	
7590 10/05/2004			EXAMINER		
LOWE HAUPTMAN GILMAN & BERNER, LLP			DANG, T	RUNG Q	
Suite 310 1700 Diagonal	Road		ART UNIT	PAPER NUMBER	
Alexandria, VA 22314			2823		

DATE MAILED: 10/05/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

					M		
		Applicat	ion No.	Applicant(s)			
Office Action Summary		10/722,3	394	WU, HSIN-CHANG			
		Examine	r	Art Unit			
		Trung Da		2823			
Period f	The MAILING DATE of this communion or Reply	ication appears on th	e cover sheet w	ith the correspondence add	ress		
THE - External control	HORTENED STATUTORY PERIOD FOR MAILING DATE OF THIS COMMUNI ensions of time may be available under the provisions or SIX (6) MONTHS from the mailing date of this common expension of the provision of the provisio	CATION. of 37 CFR 1.136(a). In no evalunication. D) days, a reply within the statutory period will apply and will, by statute, cause the ap	vent, however, may a latutory minimum of thir will expire SIX (6) MON plication to become Al	reply be timely filed ty (30) days will be considered timely. ITHS from the mailing date of this com BANDONED (35 U.S.C. § 133).	nmunication.		
Status							
1)	Responsive to communication(s) file	d on .					
· —		2b)⊠ This action is i	non-final.				
- '=	☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is						
	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.						
Disposit	tion of Claims						
4)⊠	☑ Claim(s) <u>1-18</u> is/are pending in the application.						
	4a) Of the above claim(s) is/are withdrawn from consideration.						
5)[Claim(s) is/are allowed.						
6)🖂	⊠ Claim(s) <u>1-18</u> is/are rejected.						
7)	Claim(s) is/are objected to.						
8)□	Claim(s) are subject to restric	tion and/or election	requirement.				
Applicat	tion Papers						
9)[The specification is objected to by the	e Examiner.					
•	10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.						
,	Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
	Replacement drawing sheet(s) including		•		R 1.121(d).		
11)[The oath or declaration is objected to	•	-				
Priority	under 35 U.S.C. § 119						
12)	Acknowledgment is made of a claim	for foreign priority ur	nder 35 U.S.C. 8	§ 119(a)-(d) or (f).			
	All b) Some * c) None of: 1. Certified copies of the priority	documents have be	en received.				
	2. Certified copies of the priority	documents have be	en received in A	application No			
	3. ☐ Copies of the certified copies	• •		received in this National S	stage		
	application from the Internatio	·	* **				
* ;	See the attached detailed Office actio	n for a list of the cer	tified copies not	received.			
A44 1	4/a)						
Attachmei	nt(s) ce of References Cited (PTO-892)		4) Intention	Summary (PTO-413)			
	ce of Praftsperson's Patent Drawing Review (P	TO-948)	Paper No(s)/Mail Date			
3) Info	rmation Disclosure Statement(s) (PTO-1449 or			nformal Patent Application (PTO-	152)		
Pap	er No(s)/Mail Date		6)	 ·			

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1-3, 6-9, and 13-18 are rejected under 35 U.S.C. 102(b) as being anticipated by Uglow et al. (US 6,251,770 B1).

With reference to Fig. 8A, the reference teaches the claimed invention in that it discloses a method for forming a dielectric layer comprising the steps of:

providing a first dielectric layer 102; and

in-situ forming a second dielectric layer 204 having a first portion on said first dielectric layer and a second portion on said first portion, wherein said first portion has a first dielectric constant higher than said second portion has.

See col. 7, lines 1-32 in conjunction with Figs. 8A-8B for the disclosure of the dielectric layer **204** having a bottom portion (corresponding to the claimed first portion), and a topmost portion (corresponding to the claimed second portion) of carbon-doped silicon dioxide (SiOC) with high concentration. The bottom portion further comprises a lower portion of un-doped silicon dioxide and an upper portion

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of SiOC with low carbon concentration. The un-doped silicon dioxide is known to have dielectric constant of about 4.1 (col.1, line 37). The SiOC topmost portion has dielectric constant of about 2.7 (col. 7, lines 10-11; lines 29-31), lower than that of the bottom portion. Note that, although the reference is silent about the adhesive property of the bottom portion of the dielectric layer 204, such property is held inherent because the bottom portion has either zero or very low carbon content, absent evidence to the contrary.

For claims 6, 7, 13 and 14 see col. 2, lines 40-42; col. 4, lines 55-57 and col.7, lines 1-11 for the claimed in-situ forming step comprises PECVD, and the deposition having a first precursor (i.e., no carbon or low carbon concentration) for forming the bottom portion and a second precursor (i.e., high carbon concentration) for forming the topmost portion.

For claim 8, it is inherent that the un-doped silicon dioxide portion of the bottom portion has a hardness higher than the carbon-doped silicon dioxide topmost portion because un-doped silicon dioxide is known to have mechanical strength larger than that of carbon-doped silicon dioxide (reference to Andideh et al. is cited to show this fact but not used in the rejection).

For the structure claim 15, absent evidence to the contrary, the upper portion of SiOC with low carbon concentration of the bottom portion is inherently having dielectric constant around 2.8 to 3.5 as claimed because the dielectric constant of the dielectric layer 204 decreases from 4.1 (un-doped silicon dioxide portion) to 2.7

(topmost SiOC portion) as the concentration of carbon increases from zero to a predetermined value (see Figs. 8B), and, hence the claimed values from 2.8 to 3.5 must be reached before the dielectric constant dropped to 2.7.

For claims 16 and 17, see col. 4, line 40-42 for materials of the first dielectric layer 102.

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claims 4-5, 10-12 are rejected under 35 U.S.C. 103(a) as being unpatentable over Uglow et al. as above in view of Lee et al. (US 6,663,973 B1).

Uglow teaches a method for forming a dielectric layer as described above.

The difference between Uglow and the claims is that while Uglow forms the dielectric film 204 having varying dielectric constant by increasing precursor gas flow so as to decrease the dielectric constant of the film from a high value to a low value, the claims call for a decrease in bias power from a high value to a low value to effectuate the same. However, Lee teaches that precursor gas flow rate and power level have profound effects on the dielectric constant of the film. That is,

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under the same flow rate, increasing power level will result in a film of higher dielectric constant. On the other hand, under the same power level, increasing flow rate will result in a film of lower dielectric constant (col. 16, lines 15-26 and lines 63-67). It would have been obvious to one of ordinary skill in the art to modify Uglow's process by, while keeping the same gas flow rate, executing the chemical vapor deposition under high bias power for forming the bottom portion having high dielectric constant and then decreasing the bias power for forming the topmost portion having low dielectric constant as taught by Lee because employing alternate methods recognized in the art to achieve the same result would have been within the level of one skilled in the art. For claims 5 and 11, see Lee, col. 20, lines 5-33 for the plasma chemical vapor deposition utilizing high power that would be produced by high frequency radio frequency (HFRF).

Claim Rejections - 35 USC § 112

- 5. The following is a quotation of the second paragraph of 35 U.S.C. 112:
 The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.
- 6. Claim12 is rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claim 12 recites the limitations "said first bias" and "said second bias" in lines 22-23. There is insufficient antecedent basis for this limitation in the claim.

8. Any inquiry concerning this communication or earlier communications from

the examiner should be directed to Trung Dang whose telephone number is 571-

272-1857. The examiner can normally be reached on Mon-Friday 9:30am-6:00pm.

If attempts to reach the examiner by telephone are unsuccessful, the

examiner's supervisor, Olik Chaudhuri can be reached on 571-272-1855. The fax

phone number for the organization where this application or proceeding is assigned

is 703-872-9306.

Information regarding the status of an application may be obtained from the

Patent Application Information Retrieval (PAIR) system. Status information for

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Should you have questions on access to the Private PAIR system, contact the

Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Trung Dang **Primary Examiner**

My Dany

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9/29/04